

ABSTRACT

5 A method for evaluating pickup property of the present disclosure includes preparing a laminate including at least a base layer, an adhesive layer, and a wafer having a thickness of 10 to 100 μm in order, singulating the wafer into a plurality of chips having an area of 9 mm^2 or less, pushing a center portion of the chip from a side of the base layer, and measuring an edge peeling strength when an edge of the chip is peeled off from the adhesive layer.

Fig. 2